IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

application of: Lee et al.

Attorney Docket No.:

NOVLP033X1/NVLS-000498X1

blication No.: 10/649,351

Examiner: Pham, Thanhha S.

Filed: August 26, 20003

Group: 2813

Title: METHOD FOR REDUCING

TUNGSTEN FILM ROUGHNESS AND

IMPROVING STEP COVERAGE

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on May 1, 2006 in an envelope addressed to the Commi ssioner for Patents, P.O. Box 1450

INFORMATION DISCLOSURE STATEMENT BEFORE FINAL ACTION OR NOTICE OF ALLOWANCE (37 CFR §§ 1.56 AND 1.97(c))

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449, a copy of which is attached, may be material to examination of the above-identified patent application. Applicants submit this reference in compliance with their duty of disclosure pursuant to 37 CFR §§1.56 and 1.97. The Examiner is requested to make this citation of official record in this application.

This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that this reference indeed constitutes prior art.

This Information Disclosure Statement is being filed after the mailing date of the first Office Action on the merits, or after three months of the filing date of this application, whichever event occurred last, but it is believed before the mailing date of either: (i) a final action under §1.113 or (ii) a notice of allowance under §1.311, whichever occurs first.

Accomp	anyi	ing this Information Disclosure Statement is
[a statement as specified in 37 CFR 1.97(e); or
	\times	the fee set forth in 37 CFR 1.17(p).

If fees are due, enclosed is our Check No. 11896 for \$180.00 in payment of the Information Disclosure Statement Fee. If it is determined that any additional fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 500388 (Order No. NOVLP033X1).

Respectfully submitted, BEYER WEAVER & THOMAS, LLP

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P.O. Box 70250 Oakland, CA 94612-0250 Form 1449 (Modified)

Atty Docket No. Application No.:

NOVLP033X1/NVLS000498X1

Applicant:

Applicant:

Lee et al.
Filing Date
Group

August 26, 2003

1762

U.S. Patent Documents

Examiner						Sub-	Filing
Initial	No.	Patent No.	Date	Patentee	Class	class	Date
	A 1	5,956,609	09.1999	Lee et al.			
	A2	2003/0104126 A1	06.2003	Fang et al.			

Foreign Patent or Published Foreign Patent Application

Examiner		Document	Publication	Country or		Sub-	Trans	ation
Initial	No.	No.	Date	Patent Office	Class	class	Yes	No

Other Documents

		Other Documents					
Examiner							
Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication					
	C1	Levy et al., "Deposition of Tungsten Nitride", Novellus Systems, Inc., filed					
		December 16, 2005, Application No. 11/305,368, pages 1-39.					
		[NOVLP063D1/NVLS-2615D1].					
	C2	U.S. Office Action mailed December 28, 2005, from U.S. Application No.					
		10/815,560 [NOVLP096/NVLS-2902].					
	C3	U.S. Office Action mailed April 17, 2006, from U.S. Application No. 10/815,560					
		[NOVLP096/NVLS-2902].					
	C4	Wongsenakhum et al., "Reducing Silicon Attack and Improving Resistivity of					
		Tungsten Nitride Film", Novellus Systems, Inc., filed February 6, 2006, Applicati					
		No. 11/349,035, pages 1-26. [NOVLP138/NVLS-3094]					
Examiner		Date Considered					

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.